

Atty. Docket No. CPAC 1017-5  
Appl. No. 10/632,552

PATENT

FILED ELECTRONICALLY ON 22 MAY 2006

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Marcos KARNEZOS ) Examiner: Chris C. CHU  
Application No.: 10/632,552 )  
Filed: August 2, 2003 ) Group Art Unit: 2815  
Title: **Semiconductor multi-package module having** )  
**package stacked over die-up flip chip** )  
**ball grid array package and having wire** )  
**bond interconnect between stacked packages** )  
) Date: May 22, 2006.

MAIL STOP AMENDMENT  
COMMISSIONER FOR PATENTS  
P.O Box 1450  
ALEXANDRIA, VA 22313-1450

## AMENDMENT

Dear Sir:

In response to the Office action mailed December 20, 2005, kindly amend the application as follows.

**Amendments to the Claims** are reflected in the **Listing of Claims** which begins on page 2 of this paper.

**Remarks** begin on page 6 of this paper.